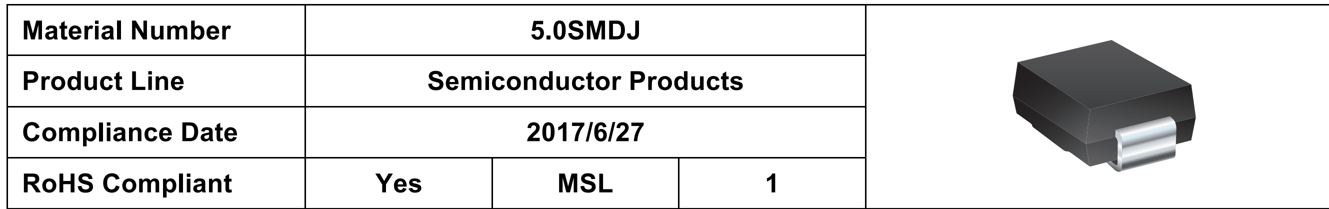
MATERIAL DECLARATION SHEET



Material Number	5.0SMDJ		
Product Line	Semiconductor Products		
Compliance Date	2017/6/27		
RoHS Compliant	Yes	MSL	1

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Outside Lead finish	Matte tin	0.001276	Tin	7440-31-5	100.000	0.433%	0.433%
2	Molding compound	ELER-8 compound	0.109750	Silica	14808-60-7	76.000	28.333%	37.280%
				Epoxy resin	25928-94-3	9.000	3.355%	
				Phenolic resin-A,B	9003-35-4	8.000	2.982%	
				Hydroxide metal	21645-51-2	6.000	2.237%	
				Carbon black	1333-86-4	1.000	0.373%	
3	Lead frame	Copper	0.125867	Copper	7440-50-8	99.800	42.669%	42.755%
				Iron	7439-89-6	0.150	0.064%	
				Phosphorus	7723-14-0	0.050	0.021%	
4	Die attach (solder)	Solder paste	0.039950	Tin	7440-31-5	5.000	0.679%	13.570%
				Lead (1)	7439-92-1	92.50	12.553%	
				Silver	7440-22-4	2.500	0.339%	
5	Chip	Silicon	0.017550	Silicon	7440-21-3	60.18	3.588%	5.961%
		Driver in		Phosphorous	7723-14-0	0.01	0.0006%	
				Boron	7440-42-8	0.01	0.0006%	
		Metallization		Nickel	7440-02-0	14.8	0.882%	
		Passivation		Lead (2)	7439-92-1	12.5	0.745%	
				Silicon dioxide	7631-86-9	10.0	0.596%	
				Aluminum oxide	1344-28-1	2.5	0.1490%	
		Total weight	0.294393					

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This Document was updated on: 2017/6/14

Important remarks:

It is the responsibility of the user to verify they are accessing the latest version.
RoHS Excepted

1. **7(a) Lead in high melting temperature type solders (i.e. lead- based alloys containing 85% by weight or more lead).**
2. **7(c)-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound**

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